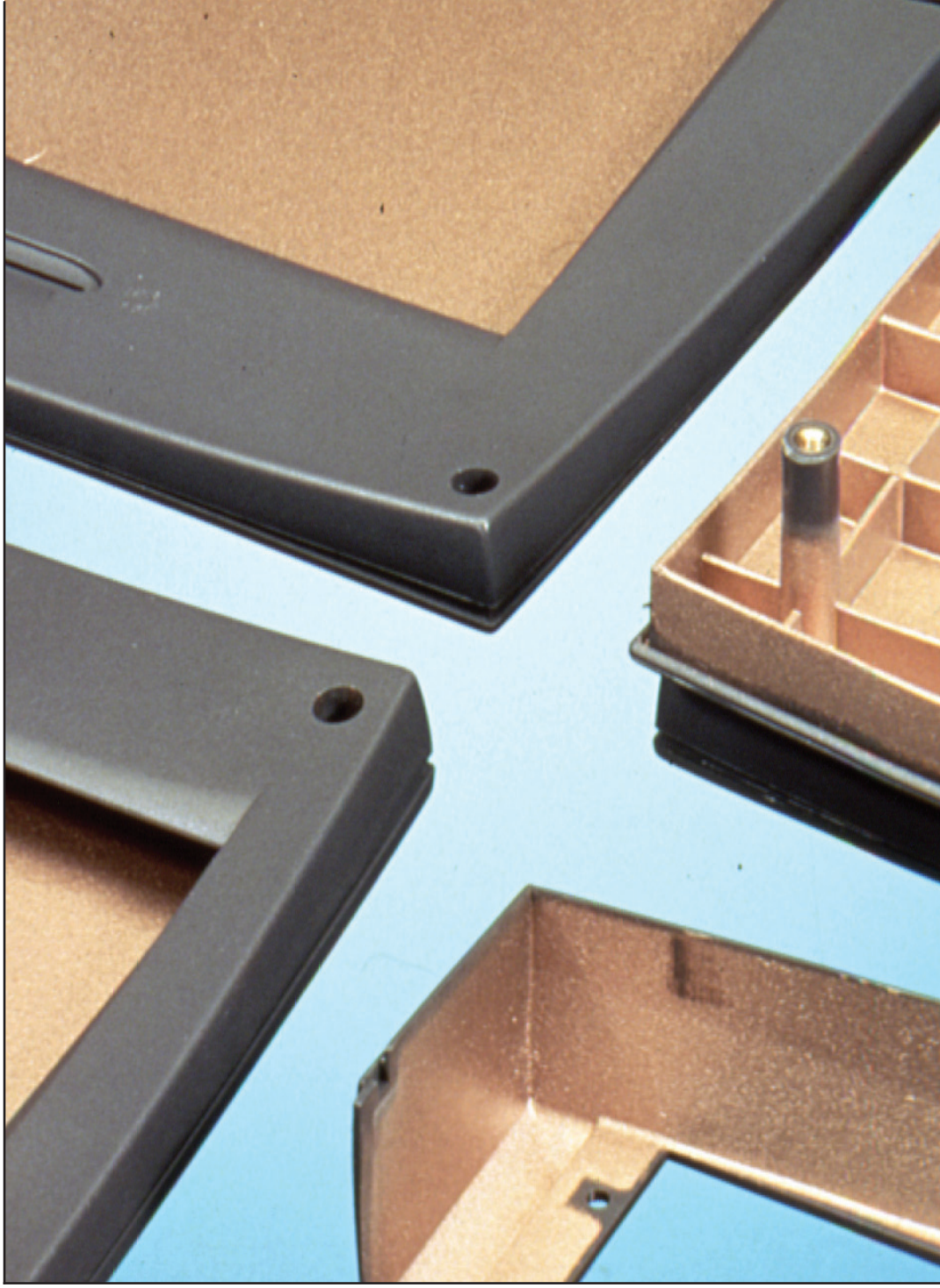
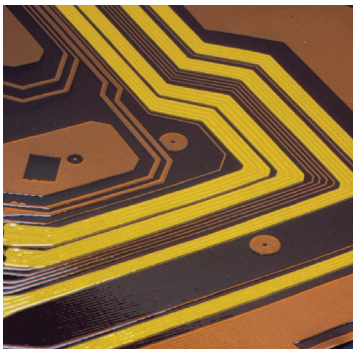
aerospace
climate control
electromechanical
filtration
fluid & gas handling
hydraulics
pneumatics
process control
sealing & shielding



Conductive Compounds Selector Guide

Conductive adhesives, sealants, coatings, greases and inks



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Compounds Selector Guide - Most Popular Materials

Silver Epoxy:

All Purpose Silver Epoxy

CHO-BOND® 584-29 is a two-component, highly conductive silver-filled epoxy adhesive, combining the good adhesive properties of epoxy with the superior conductivity of silver. In addition to being available in bulk form, the CHO-BOND 584-29 material is offered in pre-measured syringe kits and CHO-PAKs™ for rapid application.

CHO-BOND 584-29 meets the most exacting electrical bonding requirements without the high temperatures, fluxes and expensive preparatory techniques usually needed to obtain effective lead-tin solder joints.

CHO-BOND 584-29, prepared at the recommended elevated cure schedule, exhibits a volume resistivity of 0.002 ohm-cm and is usable over a wide temperature range. Adhesion to copper, bronze, cold-rolled steel, aluminum, magnesium, nickel, ceramic, phenolic and plastic is excellent.

Conductive Silicone Adhesives & Sealants:

Highly Conductive Adhesive-Sealant Silver Silicone

TECKNIT® 0002 is a pure silver filled, one component RTV silicone adhesive-sealant. It is ready to use without mixing and cures quickly at room temperature on exposure to moisture in the air to form a flexible, resilient conductive bond or seal.

TECKNIT 0002 can be used to bond or install various conductive silicone elastomer EMI gaskets or join strips of conductive elastomers to form continuous shield/seal rings or gaskets. It may also be used as a form-in-place conductive gasket to attach shielded windows to frames or bezels, and in turn, installing the framed window on a shielded enclosure or used as a form-in-place EMI gasketing material for grooves in cast boxes or covers or as a conductive seam sealant.

General Purpose Adhesive-Sealant Silver Silicone

CHO-BOND® 1038 is an electrically conductive, one-component silicone adhesive-sealant that may be used for bonding EMI gaskets or for providing EMI and environmental protection as a caulk. This material cures on exposure to atmospheric moisture and contains no acetic acid or other corrosive agents.

Cured CHO-BOND 1038 remains flexible and conductive at temperatures from -55°C to 125°C. Uncured CHO-BOND 1038 is a smooth, non-flowing paste that may be knife-spread or applied directly to a vertical surface.

CHO-BOND 1038 forms a cured skin within two minutes after exposure to atmospheric moisture and therefore must be tooled within this time period. A full cure is obtained after room temperature aging at 50% relative humidity for one week. In many cases, a good set is obtained within 8 hours. Priming the substrate with CHO-BOND 1086 is recommended.

Heat Accelerated Adhesive Two Part Silicone

CHO-BOND® 1029 is a highly conductive silicone adhesive, intended for bonding Chomerics' conductive silicone EMI gaskets to electrically conductive substrates. It is a two-component silver-plated-copper filled system, which cures to a flexible, permanent bond. Unlike one-part conductive RTV adhesives, its cure can be accelerated with heat.

CHO-BOND 1029 should not be used as an EMI caulk. The material is highly conductive through a bond line of less than 0.20 mm, however the electrical conductivity of CHO-BOND 1029 sharply decreases when the thickness is increased.

Each component of CHO-BOND 1029 is pigmented to give a uniform pink color when thoroughly mixed. Metal substrates must be coated with Chomerics' CHO-BOND 1085 or 1087 Primer before the adhesive is applied. Primer and adhesive should be stored at room temperature.

Aluminum Compatible Adhesive-Sealant Silver-Aluminum Silicone

CHO-BOND® 1075 is an electrically conductive, one component silicone adhesive-sealant that may be used for bonding EMI gasketing or for providing EMI and environmental protection as a caulk. This material cures on exposure to atmospheric moisture, and contains no acetic acid or other corrosive agents.

CHO-BOND 1075 adhesive is unique as it utilizes a silver-plated aluminum filler which provides compatibility when bonding CHO-SEAL® 1285 conductive gaskets. It is also contains no organic solvent, which eliminates solvent evaporation and odors while providing minimal shrinkage.

Cured CHO-BOND 1075 remains flexible and conductive at temperatures of -55°C to 200°C. Uncured CHO-BOND 1075 may be knife-spread or applied directly to a vertical surface.

CHO-BOND 1075 forms a cured skin within 20 minutes after exposure to atmospheric moisture and must be tooled within this time period. A full cure is obtained after room temperature curing at 50% relative humidity for one week. Priming the substrate with CHO-BOND 1086 is recommended.

Two Part Flexible Adhesive-Sealant Silver-Glass Silicone

TECKNIT 0036 is an electrically conductive, medium viscosity, RTV silicone adhesive-sealant. This silver-plated glass filled system is formulated with a special conductive material producing unique advantages. After full cure, the resultant bond or seal is flexible, resilient and conductive.

TECKNIT 0036 is recommended whenever an electrically conductive flexible bond and seal is required. This product is also used to join and install a variety of conductive elastomers and porous or open wire mesh gaskets.

One Part Flexible Sealant Silver-Glass Silicone

CHO-BOND® 1035 sealant is an electrically conductive, one-component RTV silicone, which provides both environmental sealing and EMI/RFI shielding. This sealant, filled with silver plated glass particles, contains no acetic acid and cures in the presence of moisture. Although skin formation takes only a few minutes, full properties develop in one week. CHO-BOND 1035 sealant is ideal for shelter applications where EMP or vibration is not a factor. This product should be stored at room temperature, 65-75°F (18-24°C), only.

Conductive Sealants:

Ever-Flexible Sealant Silver-Copper Isobutylene

CHO-BOND® 4660 caulking compound is a single-component, electrically conductive, paste-like material intended for EMI shielding and grounding applications. Its non-hardening characteristic makes the material particularly suited for shielding joints and seams which are likely to be disassembled, or joints subject to vibration, warping, or temperature-induced displacement.

This compound consists of Chomerics' silver-bearing powder dispersed in a binder of polyisobutylene. The formulations remain permanently flexible and adherent, with no tendency to crack or pull away from the surface. The material exhibits good chemical resistance to acids, alkalis, aqueous inorganic salts, oxygen and ozone, but is attacked by strong oxidizing agents (such as hot nitric acid) and halogens (fluorine, chlorine, etc.).

A major advantage of CHO-BOND 4660 is reduced cost. Its low density permits twice as much coverage per pound as other conductive caulking compounds.

Gap Filler & Sealant Copper Urethane

CHO-BOND® 2165 conductive sealant is a stabilized-copper-filled, two-component polyurethane. It has excellent electrical and physical properties for aerospace and military applications. CHO-BOND 2165 sealant is highly resistant to aircraft fluids and to corrosion. It contains non-chromate inhibitors to prevent copper oxidation and minimize corrosion on metal substrates.

The material is supplied in kit form. It is easily applied with a spatula or caulking gun. CHO-BOND® 2165 achieves full properties in less than 4 hours with a combination room temperature cure plus a 125°C cure, or in 24 hours at room temperature. It is tack-free in 4 hours.

Cured CHO-BOND® 2165 sealant will survive 2,000 hours in salt spray (MIL-STD-810C). It is recommended for applications in corrosive environments.

Conductive Coatings:

High Performance Coating Silver Epoxy

CHO-SHIELD® 596 coating is a two-component, silver-bearing, highly conductive epoxy paint designed to provide EMI shielding when applied to a dielectric substrate. It is also useful for coating flanges for salt spray corrosion protection when mounting an electrically conductive gasket between the surfaces.

CHO-SHIELD 596 dries to the touch in less than 1 hour at room temperature and attains full chemical resistance after 1 week at room temperature. However, the best electrical properties are achieved by curing at elevated temperatures.

Commercial Grade Coating Silver & Silver-Copper Acrylic

CHO-SHIELD® 2056 conductive coating is a high performance, acrylic system specially formulated for application to plastics. A hybrid combination of silver-plated copper and pure silver provides high levels of EMI shielding for electronic enclosures and assemblies. The superior electrical conductivity of CHO-SHIELD 2056 paint allows for thinner applied coatings, saving time and money in processing. Thinner coatings limit material wastage due to overspray and reduce the frequency of mask washing steps.

High Performance Silver Urethane

CHO-SHIELD® 4994 is a smooth, highly conductive flexible silver-filled polyurethane coating designed for military/aerospace airframe applications. This coating provides superior adhesion, excellent solvent rub and wear resistance, and is resistant against numerous operational and environmental fluids. CHO-SHIELD 4994 can be applied to aluminum as well as non-conductive substrates and is designed to be used with primers and with external topcoat systems. CHO-SHIELD 1091 can be used as a primer for ensuring improved performance on aluminum substrates.

Flange Protection Coating Copper Urethane

CHO-SHIELD® 2001 and 2002 electrically conductive coatings provide corrosion protection for enclosure flanges, which mate with EMI shielding gaskets. They can also provide a corrosion resistant conductive surface coating on aluminum or plastic substrates.

These tough, urethane coatings offer a highly conductive interface which improves overall EMI shielding performance. When used as a coating on a composite or other non-conductive surface, they provide the conductivity necessary to achieve excellent shielding effectiveness while maintaining their stability in hostile environments. CHO-SHIELD 2000-series coatings are three-part, copper-filled urethanes whose filler systems have been treated to remain electrically stable at elevated temperatures. A number of stabilizers prevent the copper from corroding in high humidity and/or marine environments.

CHO-SHIELD 2001 contains soluble chromates to minimize the effects of galvanic corrosion of the aluminum substrate, even in the event of a coating scratch. The CHO-SHIELD 2002 coating, primarily intended for composite substrates or as a 2001 repair coating, is chromate-free.

The user, through its own analysis and testing, is solely responsible for making the final selection of the system and components and assuring that all performance, endurance, maintenance, safety and warning requirements of the application are met. The user must analyze all aspects of the application, follow applicable industry standards, and follow the information concerning the product in the current product catalog and in any other materials provided from Parker or its subsidiaries or authorized distributors.

Conductive Compounds Selector Guide - Standard Materials

	Family	Product	Filler	Resin Type (Parts)	Specific Gravity [18]	Max. Vol. Resistivity [18]	Max. Surface Resistance [18] @ (Rec. Thickness [17])	Min. Lap Shear [18]		Elevated Cure Schedule	RT Cure Schedule	Working Life	Shelf Life	Recommended Primer [12]	Packing Size		Theoretical Coverage @ (Rec. Thickness [17])		VOC [7]	Hazardous Shipping Required [8]	Samples Availability	Typical Application	Comments
					g/mL	ohm-cm	ohm/sq. (mils)	psi	kPa	Time @ °F (°C)	Time	Minutes	Months		U.S. [21]	Metric	ft^2/g (mils)	m^2/g (µ)	g/L		Note 9		
Conductive Adhesives	CHO-BOND	584-29	Ag	Epoxy (2) [584]:[29] 100:6.3	2.5	0.002	n/a	1200	8274	0.25 hr. @ 235°F (113°C) 19	24 hr.	30	9	n/a	0.035 oz. to 1 lb. 10	1 to 454 g [10]	n/a (1)	n/a (25)	0	No	+++	Bonding enclosures; connnector shielding	General purpose; light paste; fast heat or RT cure; 0.025 - 0.127 mm bond lines; available in easy mix packs & syringes
Conductive Adhesives	CHO-BOND	584-208	Ag	Epoxy (2) [584]:[208] 100:100	2.7	0.005	n/a	700	4826	0.75 hr. @ 212°F (100°C)	24 hr.	60	9	n/a	3 oz. & 1 lb.	85 & 454 g	n/a (1)	n/a (25)	0	No	+	Bonding enclosures	General purpose; medium paste; fast heat or RT cure; easy 1:1 mix ratio (wt.); 0.025 - 0.127 mm bond lines
Conductive Adhesives	TECKNIT	8116	Ag	Epoxy (2) [A]:[B 100:100	2.3	0.001	n/a	1400	9653	0.50 hr. @ 212°F (100°C) & 24 hr. @ RT	n/a	45	15	n/a	2 oz.	56.7 g	n/a (1)	n/a (25)	32	Yes	+	Bonding enclosures	Epoxy solder; accelerated heat cure only
Conductive Adhesives	CHO-BOND	360-20	Ag/Cu	Epoxy (2) [360]:[20] 100:100	5.0	0.005	n/a	1600	11032	2.0 hr. @ 150°F (66°C) 20	24 hr.	60	9 [11]	n/a	3 oz. & 1 lb.	85 & 454 g	n/a (10)	n/a (254)	0	No	+	EMI gasket attachment; bonding enclosures	General purpose; very thick paste; fast hear or RT cure; less than 0.254 mm bond lines
Conductive Sealants	CHO-BOND	4660✓	Ag/Cu	Polyisobutylene (1)	2.0	0.080	n/a	n/a	n/a	n/a	1 week [4]	30	6 [11]	n/a	4 oz. & 1.5 lb. 15	113.4 & 681 g	n/a (15)	n/a (381)	306	Yes	+	Sealing enclosure seams	Good performance in vibration or shear
Conductive Sealants	CHO-BOND	2165✓	Cu	Polyurethane (2) [A]:[B] 100:7.021	2.8	0.007	n/a	n/a	n/a	4.0 hr. @ RT & 0.5 hr. @ 257°F (125°C)	1 week [4]	60	9	n/a	0.5 pt., 1 pt. & 1 qt.	454, 1135 & 2268 g	n/a (variable)	n/a (variable)	216	Yes	+	Airframe form-in-place sealing	Corrosion resistant; paintable
Conductive Sealants	TECKNIT	0005	Ag/glass	Polyolefin (1)	1.7	0.005	n/a	n/a	n/a	n/a	24 hr.	n/a	9	n/a	1 lb.	454 g	n/a (variable)	n/a (variable)	418	Yes	+	Bonding enclosures	Flexible thixotropic cream system
Conductive Silicone Sealants/Adhesives	TECKNIT	0002✓	Ag	Silicone (1)	3.1	0.010	n/a	150	1034	n/a	72 hr. [4]	5	5.5	n/a	2 oz. [13]	56.7 g	n/a (7)	n/a (178)	9	No	+++	Bonding elastomer gaskets	Rec. bond line thickness: 0.13 mm - 6.35 mm; flexible paste
Conductive Silicone Sealants/Adhesives	CHO-BOND	1038✓	Ag/Cu	Silicone (1)	3.6	0.010	n/a	150	1034	n/a	1 week [4]	30	6 [11]	1086 [5]	4 oz. & 1 lb. [14]	113.4 & 454 g	n/a (7)	n/a (178)	111	Yes	+++	Sealing enclosure seams; airframe gap sealing; connector shielding	Rec. bond line thickness: > 0.18 mm; primer promotes adhesion
Conductive Silicone Sealants/Adhesives	CHO-BOND	1030	Ag/Cu	Silicone (1)	3.7	0.050	n/a	200	1379	n/a	1 week [4]	30	6 [11]	1086 [5]	4 oz. & 1 lb. [14]	113.4 & 454 g	n/a (10)	n/a (254)	0	Yes	+++	EMI gasket attachment	Rec. bond line thickness: < 0.25 mm; primer promotes adhesion
Conductive Silicone Sealants/Adhesives	CHO-BOND	1029✓	Ag/Cu	Silicone (2) [A]:[B] 100:250.3	3.0	0.060[3]	n/a	450	3103	0.5 hr. @ 250°F (121°C)	1 week [4]	120	6 [11]	1085 [5]	3 oz. & 1 lb.	85 & 454 g	n/a (8)	n/a (203)	0	Yes	+	EMI gasket attachment	Rec. bond line thickness: < 0.20 mm; primer promotes adhesion
Conductive Silicone Sealants/Adhesives	TECKNIT	0151 & 0152 1	Ag/Cu	Silicone (1)	3.6	0.010	n/a	150	1034	n/a	1 week [4]	n/a	9	1086 [5]	2 oz. & 1 lb. [14]	56.7 & 454 g	n/a (10)	n/a (254)	77	Yes	+	Bonding enclosures; aerospace & military applications	Primer promotes adhesion
Conductive Silicone Sealants/Adhesives	CHO-BOND	1075✓	Ag/Al	Silicone (1)	2.0	0.010	n/a	175	1207	n/a	1 week [4]	30	6 [11]	1086 [5]	2.5 oz. & 10 oz. [14]	70.9 & 283.5 g	n/a (10)	n/a (254)	0	Yes	+++	Sealing enclosure seams	Rec. bond line thickness: 0.12 mm - 0.25mm; primer promotes adhesion
Conductive Silicone Sealants/Adhesives	TECKNIT	0036✓	Ag/glass	Silicone (2) [A]:[B] 100:2.53	2.0	0.010	n/a	60	414	24 hr. @ RT & 24 hr. @ 212°F (100°C)	1 week [4]	240	9	n/a	1 lb.	454 g	n/a (10)	n/a (254)	257	Yes	+	Bonding elastomer gaskets	Rec. bond line thickness; 0.50 mm - 0.76 mm; flexible paste
Conductive Silicone Sealants/Adhesives	CHO-BOND	1035✓	Ag/glass	Silicone (1)	1.9	0.050	n/a	100	689	n/a	1 week 4	30	6 11	1086 5	2.5 oz. & 10 oz. 14	70.9 & 283.5 g	n/a (7)	n/a (178)	145	Yes	+++	Sealing enclosure seams	Rec. bond line thickness: > 0.18 mm; primer promotes adhesion
Conductive Coatings	CHO-SHIELD	2040	Ag	Acrylic (1)	1.3	n/a	0.025 (1)	n/a	n/a	10-20 min. @ RT+ 0.5 hr. @ 150°F ± 10°F (66°C ± 6°C)	24 hr.	n/a	12	n/a	1 gal.	4238g	0.054 (1)	0.0165 (1)	741	Yes	+++	Plastic enclosure shielding	Commercial grade
Conductive Coatings	CHO-SHIELD	2044	Ni	Acrylic (1)	1.2	n/a	1.000 (2)	n/a	n/a	10-20 min. @ RT+ 0.75 hr. @ 150°F ± 10°F (66°C ± 6°C)	24 hr.	n/a	9	n/a	1 gal.	3920 g	0.027 (2)	0.0082 (2)	755	Yes	+++	Plastic enclosure shielding	Commercial grade
Conductive Coatings	CHO-SHIELD	2050✓	Ag/Cu & Ag	Acrylic (1)	1.1	n/a	0.030 (1)	n/a	n/a	10-20 min. @ RT+ 0.5 hr. @ 150°F ± 10°F (66°C ± 6°C)	24 hr.	n/a	12	n/a	1 gal.	4050 g	0.047 (1)	0.0044 (25)	718	Yes	+++	Plastic enclosure shielding	Commercial grade; black version available
Conductive Coatings	CHO-SHIELD	579	Ag	Epoxy (2) [A]:[B] 100:32	1.8	n/a	0.060 (1)	n/a	n/a	1 hr. @ 250°F (121°C)	1 week	480	9	n/a	1 lb.	454 g	0.110 (1)	0.0102 (25)	357	Yes	–	Protecting EMI flanges	Low VOC version of Cho-Shield 596
Conductive Coatings	CHO-SHIELD	596✓	Ag	Epoxy (2) [A]:[B] 100:37	1.8	n/a	0.060 (1)	n/a	n/a	1 hr. @ 250°F (121°C)	1 week	480	9 [11]	n/a	1 lb.	454 g	0.110 (1)	0.0102 (25)	585	Yes	–	Protecting EMI flanges	Solvent, abrasion and high temperature resistant; corrosion resistant
Conductive Coatings	CHO-SHIELD	576	Ag	Epoxy (2) [A]:[B] 100:27.5	1.8	n/a	0.060 (1)	n/a	n/a	2 hr. @ RT + 0.75 hr.@ 150°F (66°C) + 0.75 hr. @ 210°F (99°C)	1 week	480	9	n/a	1 lb.	454 g	0.110 (1)	0.0102 (25)	560	Yes	–	Platable silver epoxy coating	Provides selective platable conductive paths on dielectric plastic substrates
Conductive Coatings	CHO-SHIELD	4994✓	Ag	Polyurethane (3) [A]:[B]:[C] 100:17.18:14.54	2.1	n/a	0.075 (1)	n/a	n/a	2 hr. RT & 40-60% RH + 2 hr. @ 130°F (55°C)	1 week	180	6	n/a	1 gal.	7200 g	0.104 (1)	0.0097 (25)	596	Yes	+	Aircraft coatings; grounding	Very smooth and very conductive; long pot life; excellent sprayability
Conductive Coatings	CHO-SHIELD	2001✓	Cu	Polyurethane (3) [A]:[B]:[C] 100:10.06:41.96	1.6	n/a	0.100 (3)	n/a	n/a	2 hr. @ RT + 0.5 hr.@ 250°F (121°C)	1 week	120	9	1091	0.5 pt., 1 pt. & 1 qt.	250, 700 & 1378 g	0.029 (3)	0.0027 (76)	543	Yes	+	Protecting EMI flanges	Corrosion protection; flange protection
Conductive Coatings	CHO-SHIELD	2002✓	Cu	Polyurethane (3) [A]:[B]:[C] 100:10.34:42.18	1.6	n/a	0.100 (3)	n/a	n/a	2 hr. @ RT + 0.5 hr.@ 250°F (121°C)	1 week	120	9	1091	0.5 pt., 1 pt. & 1 qt.	250, 700 & 1378 g	0.029 (3)	0.0027 (76)	540	Yes	+	Protecting EMI flanges	Chromate free; flange protection
Conductive Coatings	CHO-SHIELD	2003	Cu	Polyurethane (3) [A]:[B]:[C] 100:10.06:41.96	1.6	n/a	0.100 (3)	n/a	n/a	2 hr. @ RT + 0.5 hr.@ 250°F (121°C)	1 week	120	9	1091	Note 6	Note 6	0.029 (3)	0.0027 (76)	541	Yes	+	Protecting EMI flanges	Darkened version of Cho-Shield 2001

✓ = *Most Popular Materials*

Parker Chomerics

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Conductive Compounds Selector Guide - Additional Materials

	Family	Product	Filler	Resin Type (Parts)	Specific Gravity [18]	Max. Vol. Resistivity [18]	Max. Surface Resistance [18] @ (Rec. Thickness [17])	Min. Lap Shear [18]		Elevated Cure Schedule	RT Cure Schedule	Working Life	Shelf Life	Suggested Primer [12]	Packing Size		Theoretical Coverage @ (Rec. Thickness [17])		VOC [7]	Hazardous Shipping Required [8]	Samples Availability	Typical Application	Comments
					g/mL	ohm-cm	ohm/sq. (mils)	psi	kPa	Time @ °F (°C)	Time	Minutes	Months		U.S. [21]	Metric	ft2/g (mils)	m2/g (µ)	g/L		Note 9		
Conductive Adhesives	CHO-BOND	592	Ag	Epoxy (2) [A]:[B] 100:50	2.6	0.050	n/a	1500	10342	0.50 hr. @ 212°F (100°C)	1 week [4]	240	9 [11]	n/a	3 oz. & 1 lb.	85 & 454 g	n/a (1)	n/a (25)	160	Yes	+	Bonding enclosures	General purpose; nearly liquid; 0.025 - 0.127 mm bond lines; bonds dissimilar metals
	TECKNIT	0008	Ag/glass	Epoxy (2) [A]:[B] 100:140	1.9	0.020	n/a	1000	6895	0.50 hr. @ 212°F (100°C) & 24 hr. @ RT	n/a	45	15	n/a	1 lb.	454 g	n/a	n/a	16	Yes	+	Bonding enclosures	General purpose; accelerated cure only; less expensive & less conductive filler
	CHO-BOND	360-208	Ag/Cu & Ag	Epoxy (2) [360]:[208] 100:33.33	4.0	0.010	n/a	1400	9653	0.75 hr. @ 212°F (100°C) [20]	24 hr.	60	9 [11]	1086	3 oz. & 1 lb.	85 & 454 g	n/a (10)	n/a (254)	0	No	+	Bonding enclosures	Similar to 360-20, but requires no contact pressure for cure; less conductive
Conductive Sealants	CHO-BOND	4669	Ag/Cu	Polyisobutylene (1)	2.0	0.080	n/a	n/a	n/a	n/a	1 week [4]	150	6 [11]	n/a	4 oz. & 1.5 lb. [15]	113.4 & 681 g	n/a (15)	n/a (381)	340	Yes	+	Sealing enclosure seams; airframe gap sealing	Good performance in vibration or shear
Conductive Silicone Sealants/Adhesives	CHO-BOND	1121	Ag/Cu	Silicone (1)	3.6	0.010	n/a	150	1034	n/a	1 week [4]	30	12	1086 [5]	1 lb. [16]	454 g	n/a (7)	n/a (178)	0	Yes	+	Sealing enclosure seams; airframe gap sealing; connector shielding	Xylene-free version of CHO-BOND 1038; rec. bond line thickness: > 0.18 mm; primer promotes adhesion
	TECKNIT	0192 & 0193 [1]	Ag/Cu	Silicone (1)	3.8	0.040	n/a	200	1379	n/a	1 week [4]	n/a	9	0239 [5]	3.5 oz. & 14 oz.	99 & 396.9 g	n/a (10)	n/a (254)	0	Yes	+	Bonding Ag/Cu elastomer gaskets; thin bond gaps	Rec. bond line thickness: < 0.4 mm; flexible paste
	TECKNIT	0014	Ag/glass	Silicone (1)	2.0	0.010	n/a	25	172	n/a	24 hr.	n/a	9	n/a	1 lb.	454 g	n/a (7)	n/a (178)	206	Yes	+	Bonding enclosures; repair of damaged gaskets	Flexible, fast cure silicone caulk
	TECKNIT	0236	Ag/Al	Silicone (2) [A]:[B] 100:2.04	1.9	0.010	n/a	100	689	24 hr. @ RT + 24 hr. @ 212°F (100°C)	1 week [4]	n/a	9	n/a	1 lb.	454 g	n/a	n/a	259	Yes	+	Bonding Ag/Al elastomers	Thick flexible paste
	CHO-BOND	1016	Ni/C	Silicone (1)	2.2	0.950	n/a	150	1034	n/a	1 week [4]	30	9	1086 [5]	2.5 oz. & 10 oz. [14]	70.9 & 283.5 g	n/a (10)	n/a (254)	0	Yes	+	Sealing enclosure seams; airframe gap sealing; connector shielding	Ideal in outdoor applications for EMI shielding and low corrosion
	TECKNIT	0035	Ni	Silicone (2) [A]:[B] 100:2.53	4.0	0.010	n/a	50	345	24 hr. @ RT & 24 hr. @ 212°F (100°C)	1 week [4]	240	9	n/a	1 lb.	454 g	n/a (10)	n/a (254)	285	Yes	+	Bonding elastomer gaskets	Thin flexible paste
Conductive Greases	CHO-LUBE™	4220	Ag	Silicone (1)	3.1	0.100	n/a	n/a	n/a	n/a	n/a	n/a	12	n/a	4 oz. & 10 oz. [14]	113.4 & 283.5 g	n/a (1)	n/a (25)	0	No	–	Grounding	Excellent for surface-to-surface contact areas
	TECKNIT	0015 & 0016 [1]	Ag/glass	Silicone (1)	2.5	0.20	n/a	n/a	n/a	n/a	n/a	n/a	12	n/a	2 oz. & 1 lb.	56.7 & 454 g	n/a (1)	n/a (25)	0	No	–	Electrical grounding and lubricating	Contains no carbon or graphite
Conductive Coatings	TECKNIT	0025 & 0081 [1]	Ag/glass	Acrylic (1)	1.7	n/a	1.000 (2)	n/a	n/a	n/a	1 week	30	6	n/a	1 lb. & 1 gal.	454 & 3632 g	0.110 (2)	0.0102 (51)	567	Yes	+	Conductive coatings on enclosures	Thinning required for spraying, toluene is recommended
	CHO-SHIELD	611	Ag	Epoxy (2) [A]:[B] 100:36	1.8	n/a	0.060 (1)	n/a	n/a	1 hr. @ 250°F (121°C)	1 week	480	9 [11]	n/a	1 lb.	454 g	0.110 (1)	0.0102 (25)	517	Yes	–	Protecting EMI flanges	Variant of CHO-SHIELD 596
	CHO-SHIELD	598	Ag	Epoxy (2) [A]:[B] 100:25	1.9	n/a	0.060 (1.5)	n/a	n/a	1 hr. @ 75 °F (24°C) + 1 hr.@ 150°F (66°C) + 1 hr. @ 250°F (121°C)	2 week	480	9 [11]	n/a	1 lb.	454 g	0.110 (1.5)	0.0102 (37)	439	Yes	–	Protecting EMI flanges	Exceptional salt spray resistance
	CHO-SHIELD	610	Ag/Cu	Epoxy (2) [A]:[B] 100:28.25	1.2	n/a	0.150 (2)	n/a	n/a	2 hr. @ RT + 4 hr.@ 175°F (79°C)	1 week	480	9 [11]	n/a	1 gal.	3750 g	0.060 (2)	0.0056 (25)	591	Yes	+	Plastic enclosure shielding	Corrosion protection
	CHO-FLEX™	601	Ag	Polyurethane (1)	2.0	n/a	0.060 (1)	n/a	n/a	1.5 hr. @ 360°F (182°C)	n/a	n/a	6 [11]	n/a	1 lb.	454 g	0.066 (1)	0.0061 (25)	422	Yes	–	Round wire cable shielding; flexible circuit cable shielding	Screenable and flexible
	CHO-FLEX™	602	Ag	Polyurethane (2)	2.1	n/a	0.060 (1)	n/a	n/a	n/a	1 week	n/a	6 [11]	n/a	1 lb.	454 g	0.066 (1)	0.0061 (25)	XXX	Yes	–	Composites and low melt plastics	Screenable and flexible
	CHO-SHIELD	4998	Ag	Polyurethane (3) [A]:[B]:[C] 100:17.18:14.51	2.1	n/a	0.075 (1)	n/a	n/a	2 hr. RT & 40-60% RH + 2 hr. @ 130°F (55°C)	24 hr.	60	6	n/a	1 gal.	7200 g	0.104 (1)	0.0097 (25)	596	Yes	–	Aircraft coatings; grounding	Very smooth and very conductive; excellent sprayability
Conductive Inks	CHO-FLEX	4430	Ag	Polyester (1)	2.5	n/a	0.080 (0.5)	n/a	n/a	0.5 hr. @ 250°F (121°C)	n/a	n/a	9 [11]	n/a	1 lb.	454 g	0.046 (0.5)	0.0043 (13)	510	Yes	+	Membrane keyboard and sensor application	Bonds to Mylar® films; can be creased or scratched without affecting performance
Primers [12]	CHO-BOND	1085	n/a	n/a	0.82	n/a	n/a	n/a	n/a	n/a	0.5 hr.	n/a		n/a	1 pt.	400 g	n/a	n/a	744	Yes	–	Primer for Cho-Bond 1029	n/a
	CHO-BOND	1086	n/a	n/a	0.80	n/a	n/a	n/a	n/a	n/a	0.5 hr.	n/a	9	n/a	0.35 oz. & 1 pt.	10 & 375 g	n/a	n/a	740	Yes	–	Primer for moisture cured silicone	n/a
	TECKNIT	0239	n/a	n/a	0.76	n/a	n/a	n/a	n/a	n/a	0.5 hr.	n/a	9	n/a	0.5 pt.	180 g	n/a	n/a	625	Yes	–	Primer for TECKNIT 0192 & 0193	n/a
	CHO-BOND	1091	n/a	n/a	0.80	n/a	n/a	n/a	n/a	n/a	0.5 hr.	n/a	6	n/a	0.25 & 0.5 pt.	94 & 188 g	n/a	n/a	797	Yes	–	Primer for CHO-SHIELD 2000 series coatings on aluminum	n/a

NOTES:

1. Two part numbers are listed which represent the same material in a different sized containers.
2. Formerly known as 73-00008.
3. Value represents DC resistance through a 0.4 square inch by 0.008 inch thick sample.
4. Material is sufficiently cured after 24 hours for handling purposes. Full specification properties are developed after time given.
5. Primer included with product.
6. CHO-SHIELD 2003 packaging is irregular. The "-00-" size contains 250 g of CHO-SHIELD 2003 and includes 94 g of CHO-BOND 1091 primer. The "-01-" size contains 524 g coating and includes 94 g primer. The "-04-" size contains 700 g coating and includes 188 g primer.
7. Volatile Organic Content (VOC) values are theoretical approximations calculated from the characteristics of the components in the product as we know them at this time.
8. All compounds such as these should be packed and shipped by trained professionals. Regulations vary by material type and by quantity. The information provided here is to be used as a general guideline only.
9. Samples availability scale: +++ represents high sample availability with short lead times; + represents samples available for qualified applicants or with potentially long lead times; – represents that samples are generally not available unless in very specific instances.
10. CHO-BOND 584-29 is sold in 1, 2 & 10 gram ChoPaks; a 3 gram dual syringe package, bundle of 10; plus 3 oz. (85 g) & 1 lb. (454 g) bulk kits.
11. The shelf life of this product may be extended with testing, generally 3 additional months from the original expiration date. Contact Chomerics for details. Customer will need to submit an unused container or kit for testing and a fee will apply.
12. Primers are applied to the substrate prior to application of the conductive material. In no instance is the primer to be mixed into the conductive material.
13. Packed in a small aluminum tube.
14. Small size packed in a small aluminum tube; large size packed in a 6 fluid ounce Semco tube.
15. Small size packed in a small aluminum tube; large size packed in a 12 fluid ounce cartridge.
16. Packed in a 6 fluid ounce Semco tube.
17. The recommended thickness may vary from application to application. Please use the published data as an initial guideline. Contact Chomerics' Application Engineering for assistance.
18. Properties listed are for products prepared at the elevated cure schedule. Test Methods: Specific Gravity, 95-40-5504, 95-40-5502; Volume Resistivity, 95-40-5102, 95-40-5101, 95-40-6007, 95-40-6017; Surface Resistance, 95-40-5104; Lap Shear, 95-40-5300.
19. Alternative cure: 2 hrs. @ 150°F (65°C) or 0.75 hr. @ 210°F (99°C).
20. Alternative cure: 0.25 hr. @ 235°F (115°C); 1 hr. @ 200°F (95°C) or 2 hrs. @ 150°F (65°C).
21. Ounces (oz.) are weight-based, i.e., 0.0625 pound or 28.4 grams. Some conductive coatings are in volume-based units of gallons, quarts and pints.

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